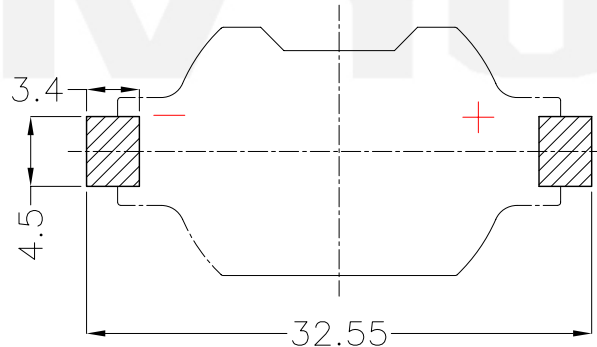
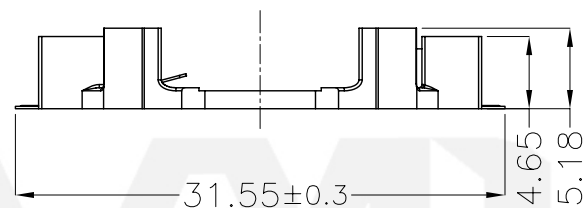
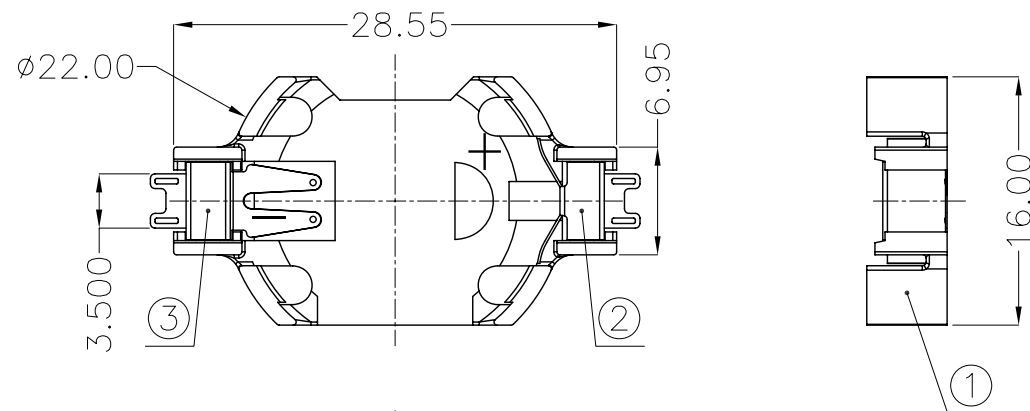




| | | | |
|------|---------|---------|------|
| REV. | ECN NO. | REVISED | DATE |
| | | | |



PCB Layout Diagram
Top View

NOTE:

1.MATERIAL:

- a.HOUSING:LCP UL94V-0
- b.CONTACT:PHOSPHOR BRONZE
(SURFACE PLATING:Au 1u")

SEE ORDERING INFORMATION

2.ELECTRIC:

- a.CONTACT RESISTANCE: 30 MILLIOHMS MAX
- b.INSULATION RESISTANCE: 1000 MEGA OHMS MIN
- c.DIELECTNIC VOLTAGE: 500V AC ONE SEC LEVEL
- d.OPERATING TEMPERATURE: -25°C~ +85°C

ORDERING INFORMATION

BS-06-B*015**

电池座系列

BS-06系列

SMT 180° TYPE

PLATING:
A-Au1U"
J-Ni100U"~120U"
K-Sn100U"~120U"

MATERIAL:
1A-PBT BLACK
1B-PA66 BLACK
2A-PPA BROWN
2B-PPA BLACK
3A-PPS BROWN
3B-PPS BLACK
4A-LCP WHITE
4B-LCP BLACK



| | | | |
|--|---------------------------------|---|-----------------|
| UNLESS OTHERWISE SPECIFIED TOLERANCES | | MYOUNG 美阳 www.meiyangdz.com | |
| DECIMALS: X :±0.30 X.X :±0.25 X.XX :±0.20 X.XXX :±0.10 | ANGLES: X :±1° X.X :±0.5° | DSND YangFeng | DATE 2017-07-11 |
| WEIGHT: 1.02g | | CHKD ZhouRuicai | DATE 2017-07-11 |
| SHEET 1 OF 1 | | APVD XueShun Yong | DATE 2017-07-11 |
| UNIT: mm | | SCALE: 2:1 | SIZE: A4 |
| REV.: A/0 | | VIEW: | OBJECT: MY |
| DRAW NO.:MY-CP-0083 | | TITLE: BS-2032-6-2 Au SMT | |
| PART NO.: BS-06-B4AA015 | | PART NO.: | |

| NO. | PART NAME | Q'TY | MATERIAL | PLATING & COLOR |
|-----|-------------|------|---------------------------|-----------------------------------|
| 3 | TERMINAL(-) | 1 | PHOSPHOR BRONZE, T=0.20mm | Gold Plating and Ni Under-Plating |
| 2 | TERMINAL(+) | 1 | PHOSPHOR BRONZE, T=0.20mm | Gold Plating and Ni Under-Plating |
| 1 | HOUSING | 1 | LCP | WHITE |